

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

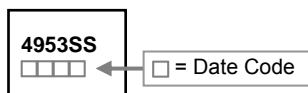
DESCRIPTION

The SSG4953 uses advanced trench technology to provide excellent on-resistance, low gate charge and operation with gate voltages as low as 2.5V. The device is suitable for use as a load switch or in PWM applications. It may be used in a common drain arrangement to form a bidirectional blocking switch.

FEATURES

- Simple Drive Requirement
- Lower On-resistance
- Low Gate Charge

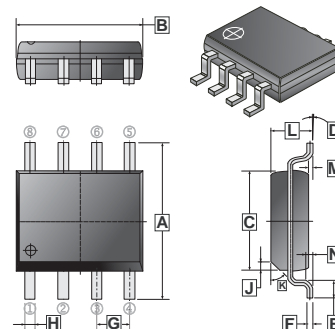
MARKING



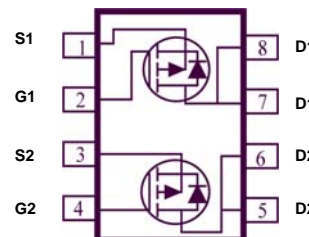
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8	3K	13' inch

SOP-8



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.80	6.20	H	0.35	0.49
B	4.80	5.00	J	0.375 REF.	
C	3.80	4.00	K	45°	
D	0°	8°	L	1.35	1.75
E	0.40	0.90	M	0.10	0.25
F	0.19	0.25	N	0.25 REF.	
G	1.27 TYP.				



MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current @ $V_{GS}=10\text{V}$ ¹	I_D	$T_A = 25^\circ\text{C}$	-6
		$T_A = 100^\circ\text{C}$	-4
Pulsed Drain Current ²	I_{DM}	-12	A
Single Pulse Avalanche Energy ³	EAS	108	mJ
Avalanche Current	I_{AS}	19	A
Total Power Dissipation ⁴	P_D	1.5	W
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55 ~ 150	$^\circ\text{C}$
Thermal Resistance Ratings			
Thermal Resistance Junction-Ambient ¹ (Max.)	$R_{\theta JA}$	83	$^\circ\text{C} / \text{W}$
Thermal Resistance Junction-Case ¹ (Max.)	$R_{\theta JC}$	60	$^\circ\text{C} / \text{W}$

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	-30	-	-	V	$V_{GS}=0V, I_D = -250\mu A$
Gate-Threshold Voltage	$V_{GS(th)}$	-1	-	-2.5	V	$V_{DS}=V_{GS}, I_D = -250\mu A$
Forward Transfer Conductance	G_{fs}	-	6	-	S	$V_{DS} = -10V, I_D = -6A$
Gate-Body Leakage	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V$
Drain-Source Leakage Current	I_{DSS}	-	-	-1	μA	$V_{DS} = -24V, V_{GS}=0$
Drain-Source On-Resistance ²	$R_{DS(ON)}$	-	-	45	m Ω	$V_{GS} = -10V, I_D = -5A$
		-	-	82		$V_{GS} = -4.5V, I_D = -4A$
Total Gate Charge	Q_g	-	6.4	-	nC	$I_D = -6A$ $V_{DS} = -20V$ $V_{GS} = -4.5V$
Gate-Source Charge	Q_{gs}	-	2.7	-		
Gate-Drain ("Miller") Charge	Q_{gd}	-	3.1	-		
Turn-On Delay Time ²	$T_{d(on)}$	-	9	-	nS	$V_{DS} = -12V$ $I_D = -5A$ $V_{GS} = -10V$ $R_G = 3.3\Omega$
Rise Time	T_r	-	16.6	-		
Turn-Off Delay Time	$T_{d(off)}$	-	21	-		
Fall Time	T_f	-	21.6	-		
Input Capacitance	C_{iss}	-	645	-	pF	$V_{GS}=0V$ $V_{DS} = -25V$ $f=1.0MHz$
Output Capacitance	C_{oss}	-	272	-		
Reverse Transfer Capacitance	C_{rss}	-	105	-		
Avalanche Characteristics						
Single Pulse Avalanche Energy ⁵	EAS	30	-	-	mJ	$V_{DD} = -25V, L=0.1mH, I_{AS} = -10A$
Source-Drain Diode						
Forward On Voltage ²	V_{DS}	-	-0.84	-1.2	V	$I_S = -1.7A, V_{GS}=0V$
Continuous Source Current ^{1,6}	I_S	-	-	-6	nS	$V_G = V_D = 0V$ Force Current
Pulsed Source Current ^{2,6}	I_{SM}	-	-	-12	nC	

Notes:

1. surface mounted on a 1 inch2 FR-4 board with 2OZ copper. 135 $^\circ\text{C}/W$ when mounted on Min. copper pad.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L=0.1mH, I_{AS} = -19A$
4. The power dissipation is limited by 150 $^\circ\text{C}$ junction temperature
5. The Min. value is 100% EAS tested guarantee.
6. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

CHARACTERISTIC CURVES

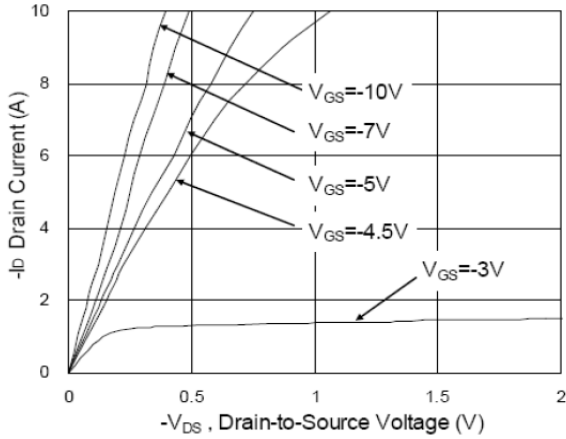


Fig.1 Typical Output Characteristics

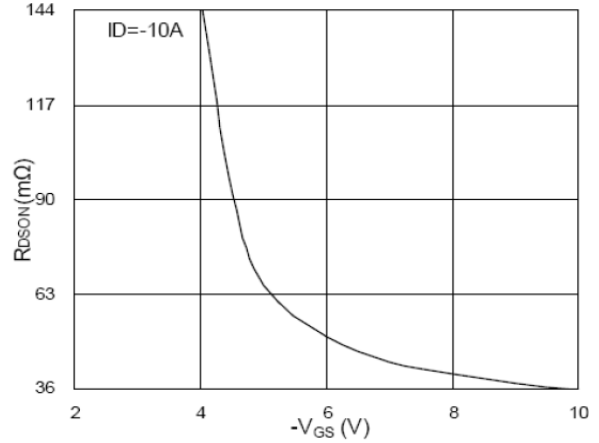


Fig.2 On-Resistance vs. Gate-Source

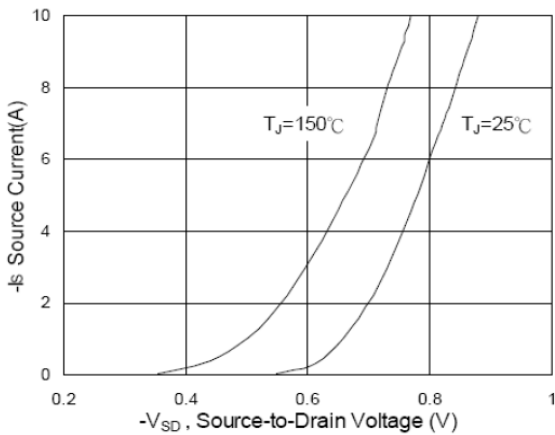


Fig.3 Forward Characteristics of Reverse

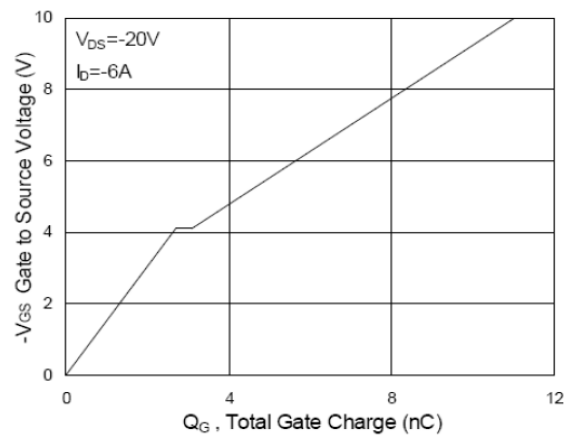


Fig.4 Gate-charge Characteristics

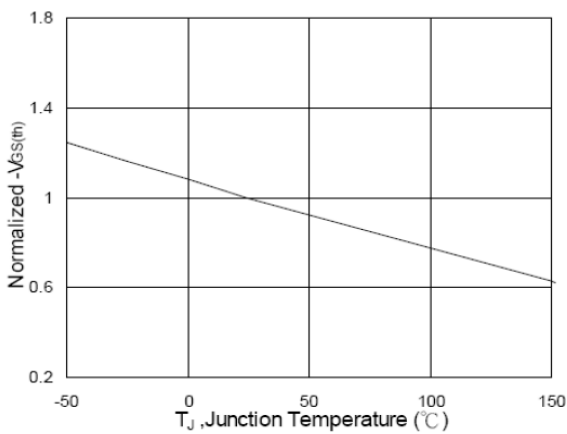


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

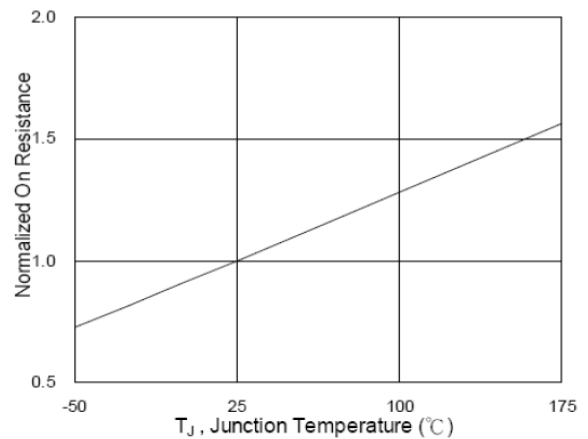


Fig.6 Normalized $R_{DS(ON)}$ vs. T_J

CHARACTERISTIC CURVES

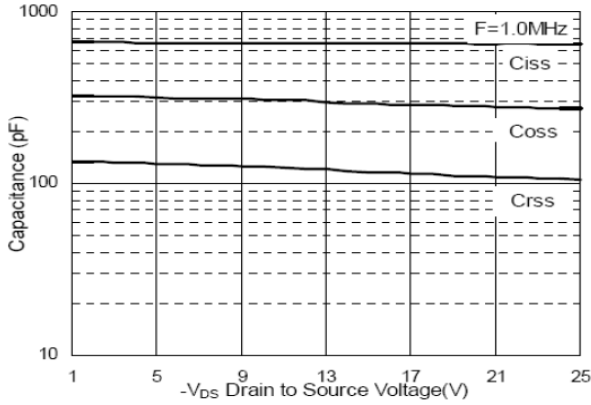


Fig.7 Capacitance

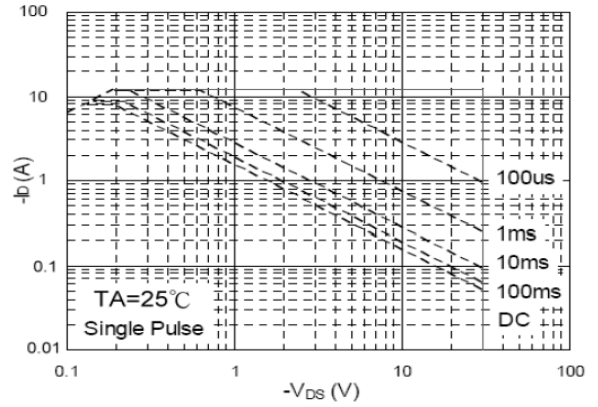


Fig.8 Safe Operating Area

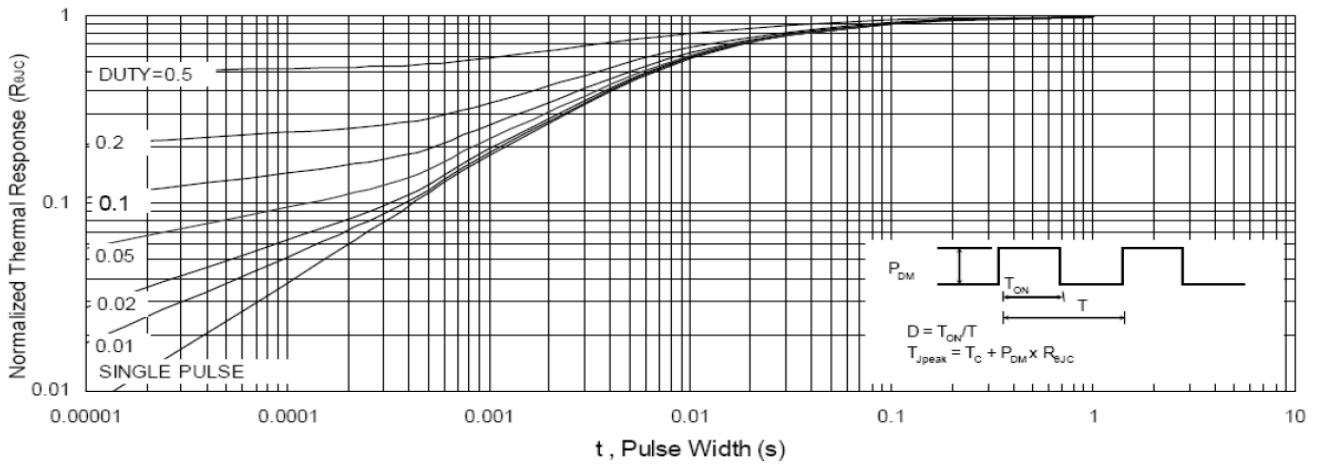


Fig.9 Normalized Maximum Transient Thermal Impedance

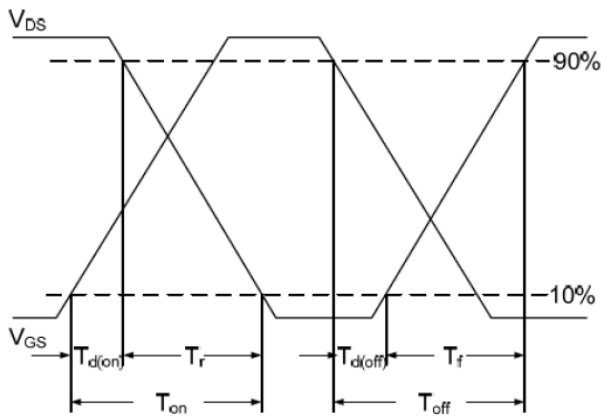


Fig.10 Switching Time Waveform

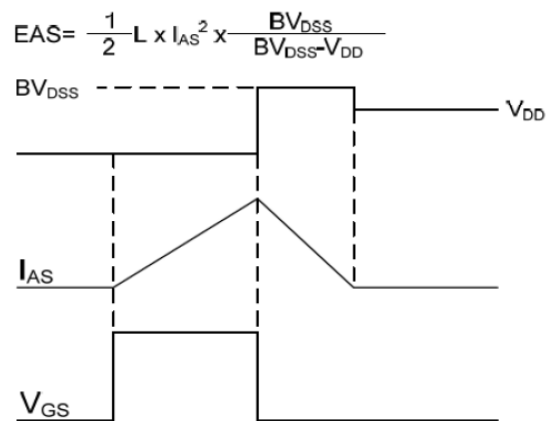


Fig.11 Unclamped Inductive Switching Wave